





ILS-TT TURNTABLE MACHINE

POWERFUL LASER SYSTEM
FOR MICRO MATERIAL PROCESSING

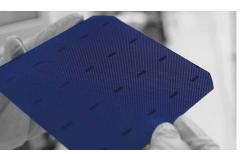


FEATURES

- Single or dual scanner setup
- Automatic camera calibration
- Automated routines for reference runs
- Automated process control
- Stand alone and production line integrated systems
- 3-, 5- or even 8-Point alignment methods available (wafer edges or fiducials)

OPTIONS

- CAD file import
- SQL data base for process and event tracking
- MES interface (SECS GEM PV2)
- Integrated process metrology
- Fully-automatic handling (production)







APPLICATIONS

Laser Contact Opening for PERC, Laser Doped Selective Emitter, Front side LCO, Laser Direct Cleaving, various applications in electronics processing

ACCURACY

 $< +/-35 \mu m$ (1 sigma) $< +/-10 \mu m$ optionally $< +/-2 \mu m$ repeatability

SUBSTRATE

Dimension up to 161 x 161 mm

Thickness > 100 μm

mono or poly crystalline silicon square/ pseudo square,

ceramic, PCB

AVAILABLE LASER SOURCES

Wavelength: 1064, 1030, 532, 515, 355 nm

Pulse: μs, ns, ps, fs

THROUGHPUT

4000 wafer per hour

